

Title (en)

MICROSPHERE CONTAINING ELECTRON BEAM CURED PRESSURE-SENSITIVE ADHESIVE TAPES AND METHODS OF MAKING AND USING SAME

Title (de)

ELEKTRONENSTRAHLAUSGEHÄRTETE HAFTKLEBSTOFFBÄNDER ENTHALTENDE MIKROSPHÄRE UND VERFAHREN ZUR HERSTELLUNG UND VERWENDUNG DERSELBEN

Title (fr)

RUBANS AUTOADHESIFS DURCIS PAR FAISCEAU ELECTRONIQUE CONTENANT DES MICROSPHERES, ET PROCEDES DE FABRICATION ET D'UTILISATION DES RUBANS AUTOADHESIFS

Publication

EP 1735147 A4 20071219 (EN)

Application

EP 04821986 A 20040414

Priority

US 2004011506 W 20040414

Abstract (en)

[origin: WO2005110737A1] The present invention provides pressure sensitive adhesive tape including at least one electron beam cured (EB-cured), rubber-based pressure sensitive adhesive (PSA) core including microspheres. The core layer is coated on at least one side, and in one embodiment, on both sides, with a skin layer including an EB-cured rubber-based PSA that is substantially free of microspheres. The core layer may comprise a lamination seam, a second core layer or a non-woven support layer.

IPC 8 full level

B32B 7/12 (2006.01); **B32B 15/04** (2006.01); **C09J 7/10** (2018.01)

CPC (source: EP US)

B32B 7/12 (2013.01 - EP US); **B32B 25/10** (2013.01 - US); **C09J 7/10** (2017.12 - EP US); **C09J 7/38** (2017.12 - EP); **C09J 7/383** (2017.12 - EP); **B32B 2305/72** (2013.01 - US); **B32B 2405/00** (2013.01 - US); **C09J 2301/124** (2020.08 - EP); **C09J 2301/1242** (2020.08 - EP); **C09J 2301/208** (2020.08 - EP); **C09J 2301/412** (2020.08 - EP); **C09J 2421/00** (2013.01 - EP)

Citation (search report)

- [XY] WO 0233017 A2 20020425 - NITTO DENKO CORP [JP], et al
- [Y] EP 1033393 A2 20000906 - NITTO DENKO CORP [JP]
- [X] US 6217981 B1 20010417 - KANNO MAMORU [JP], et al
- See references of WO 2005110737A1

Designated contracting state (EPC)

CZ DE FR GB SE

DOCDB simple family (publication)

WO 2005110737 A1 20051124; BR PI0418750 A 20070911; CN 1956845 A 20070502; EP 1735147 A1 20061227; EP 1735147 A4 20071219; JP 2007532751 A 20071115

DOCDB simple family (application)

US 2004011506 W 20040414; BR PI0418750 A 20040414; CN 200480043151 A 20040414; EP 04821986 A 20040414; JP 2007508310 A 20040414